TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π -MOSIV)

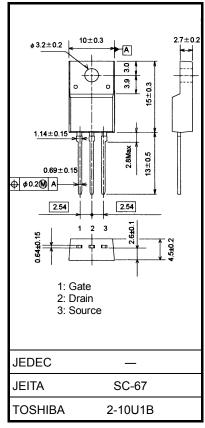
2SK3565

Switching Regulator Applications

- Low drain-source ON resistance: $RDS(ON) = 2.0 \Omega$ (typ.)
- High forward transfer admittance: $|Y_{fs}| = 4.5 \text{ S} (typ.)$
- Low leakage current: $I_{DSS} = 100 \ \mu A (V_{DS} = 720 \text{ V})$
- Enhancement mode: $V_{th} = 2.0 \sim 4.0 \text{ V} (V_{DS} = 10 \text{ V}, \text{ID} = 1 \text{ mA})$

Characteristics Symbol Rating Unit Drain-source voltage 900 ٧ VDSS 900 Drain-gate voltage ($R_{GS} = 20 \text{ k}\Omega$) V VDGR V Gate-source voltage ±30 VGSS DC 5 (Note 1) I_D Drain current Α Pulse (t = 1 ms) 15 IDP (Note 1) Drain power dissipation (Tc = 25°C) 45 w P_D Single pulse avalanche energy E_{AS} 595 mJ (Note 2) 5 Avalanche current А I_{AR} 4.5 Repetitive avalanche energy (Note 3) E_{AR} mJ °C Channel temperature T_{ch} 150 °C Storage temperature range Tstg -55~150





Weight : 1.7 g (typ.)

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc.).

Thermal Characteristics

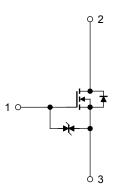
Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R _{th (ch-c)}	2.78	°C/W
Thermal resistance, channel to ambient	R _{th (ch-a)}	62.5	°C/W

Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2: V_DD = 90 V, T_{ch} = 25 ^{\circ}C(Initial), L = 43.6 mH, I_{AR} = 5.0 A, R_G = 25 Ω

Note 3: Repetitive rating: pulse width limited by maximum channel temperature

This transistor is an electrostatic-sensitive device. Please handle with caution.



Unit: mm

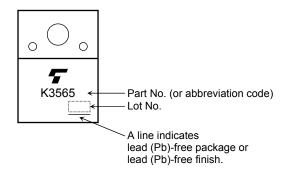
Electrical Characteristics (Ta = 25°C)

Char	acteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cui	rrent	I _{GSS}	$V_{GS}=\pm 25~V,~V_{DS}=0~V$	_		±10	μA
Gate-source brea	akdown voltage	V (BR) GSS	$I_G = \pm 10 \ \mu A, \ V_{DS} = 0 \ V$	±30		_	V
Drain cut-off curr	ent	I _{DSS}	$V_{DS} = 720 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$	_		100	μA
Drain-source bre	akdown voltage	V (BR) DSS	$I_D = 10 \text{ mA}, V_{GS} = 0 \text{ V}$	900		_	V
Gate threshold v	oltage	V _{th}	$V_{DS} = 10 \text{ V}, \text{ I}_{D} = 1 \text{ mA}$	2.0		4.0	V
Drain-source ON	resistance	R _{DS (ON)}	$V_{GS} = 10 \text{ V}, \text{ I}_{D} = 3 \text{ A}$	_	2.0	2.5	Ω
Forward transfer	admittance	Y _{fs}	$V_{DS} = 20 \text{ V}, \text{ I}_{D} = 3 \text{ A}$	2.0	4.5	_	S
Input capacitance	e	C _{iss}		_	1150	_	
Reverse transfer capacitance		C _{rss}	V_{DS} = 25 V, V_{GS} = 0 V, f = 1 MHz	_	20	_	pF
Output capacitance		C _{oss}			100	_	
Switching time	Rise time	tr	V_{GS} $0 V$ V_{GS} $0 V$ V_{GS} $0 V$	_	30		- ns
	Turn-on time	t _{on}		_	70	_	
	Fall time	t _f		_	60	_	
	Turn-off time	t _{off}	Duty \leq 1%, t _w = 10 μ s		170		
Total gate charge G		Qg		_	28	_	
Gate-source charge		Q _{gs}	$V_{DD}\simeq 400~V,~V_{GS}=10~V,~I_{D}=5~A$		17		nC
Gate-drain charge		Q _{gd}			11		

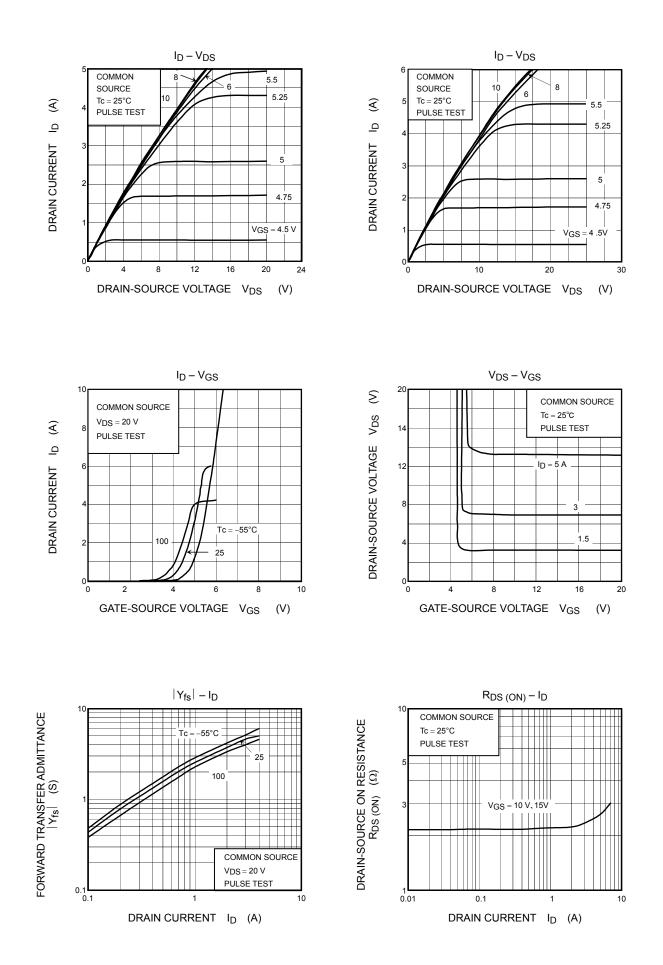
Source-Drain Ratings and Characteristics (Ta = 25°C)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I _{DR}	—	_	_	5	А
Pulse drain reverse current (Note 1)	I _{DRP}	—	_		15	А
Forward voltage (diode)	V _{DSF}	$I_{DR} = 5 \text{ A}, \text{ V}_{GS} = 0 \text{ V}$	_	_	-1.7	V
Reverse recovery time	t _{rr}	$I_{DR} = 5 \text{ A}, V_{GS} = 0 \text{ V},$	_	900		ns
Reverse recovery charge	Qrr	dl _{DR} /dt = 100 A/μs		5.4		μC

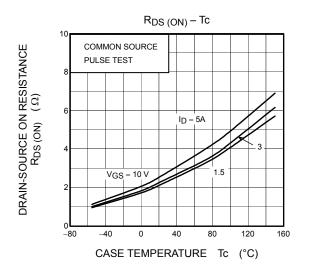
Marking

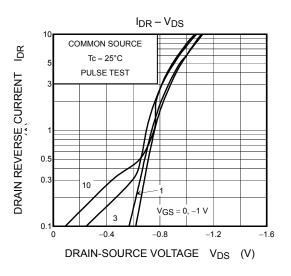


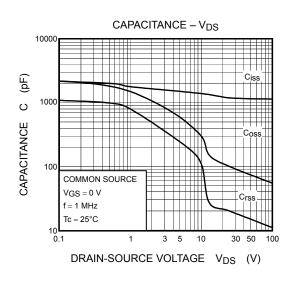
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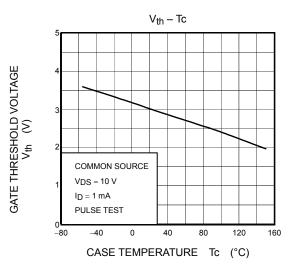


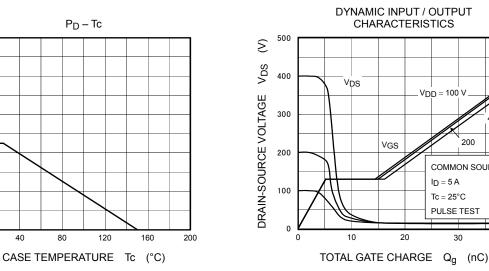


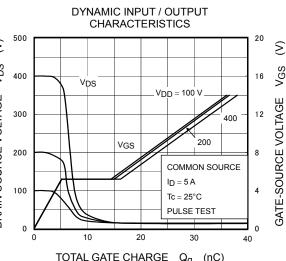
P_D – Tc

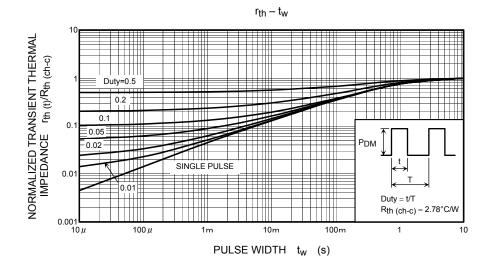
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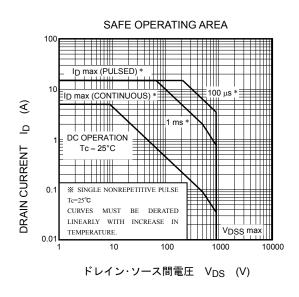
DRAIN POWER DISSIPATION PD (W)

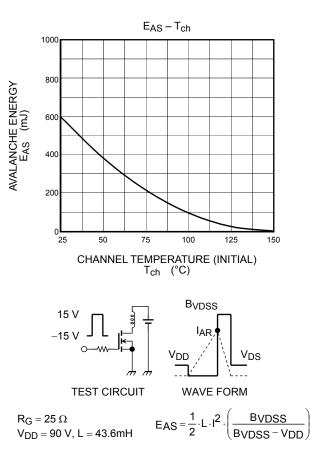












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